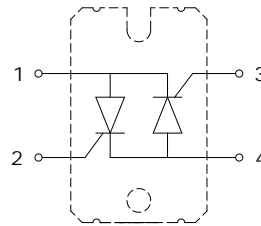


PRELIMINARY DATASHEET
**Anti-Parallel Silicon Controlled Rectifier
 1200V, 35A in SOT227 Package**

- High voltage & high current
- Low on-state voltage
- Suitable for over voltage control, motor control circuit and heating control system
- Pb-free finished; RoHS compliant


MAXIMUM RATINGS (per SCR), $T_C = 25^\circ\text{C}$ unless otherwise noted

| Parameter | Symbol | Value | Units |
|---|----------------|--------------|-----------------------------|
| Average on-state current $T_C = 70^\circ\text{C}$, $T_j = 180^\circ\text{C}$ conduction half sine wave | $I_{T(AV)}$ | 35 | A |
| Continuous RMS on-state current as AC switch | $I_{T(RMS)}$ | 55 | |
| Non-repetitive surge peak on-state current $T_j = 125^\circ\text{C}$, $t_p = 10$ ms, applied rated V_{RRM} $T_j = 125^\circ\text{C}$, $t_p = 10$ ms, no applied V_{RRM} | I_{TSM} | 500 600 | |
| I^2t value for fusing $T_j = 125^\circ\text{C}$, $t_p = 10$ ms, applied rated V_{RRM} $T_j = 125^\circ\text{C}$, $t_p = 10$ ms, no applied V_{RRM} | I^2t | 1250 1760 | A^2s |
| $I^2\sqrt{t}$ value for fusing $t = 0.1$ to 10 ms, no voltage reapplied | $I^2\sqrt{t}$ | 12500 | $\text{A}^2\sqrt{\text{s}}$ |
| Rate of rise of on-state current $T_j = 125^\circ\text{C}$ | di/dt | 100 | $\text{A}/\mu\text{s}$ |
| Peak gate current $T_j = 125^\circ\text{C}$ | I_{GM} | 2.5 | A |
| Maximum repetitive peak off-state voltage $I_R = 100\mu\text{A}$ | V_{DRM} | 1200 | V |
| Maximum repetitive reverse voltage $I_R = 100\mu\text{A}$ | V_{RRM} | 1200 | |
| Maximum reverse leakage current $T_j = 25^\circ\text{C}$ $T_j = 125^\circ\text{C}$ | I_{RRM} | 0.5 10 | mA |
| Maximum direct leakage current $T_j = 25^\circ\text{C}$ $T_j = 125^\circ\text{C}$ | I_{DRM} | 0.5 10 | |
| Operating junction and storage temperature | T_j, T_{stg} | -40... +125 | $^\circ\text{C}$ |

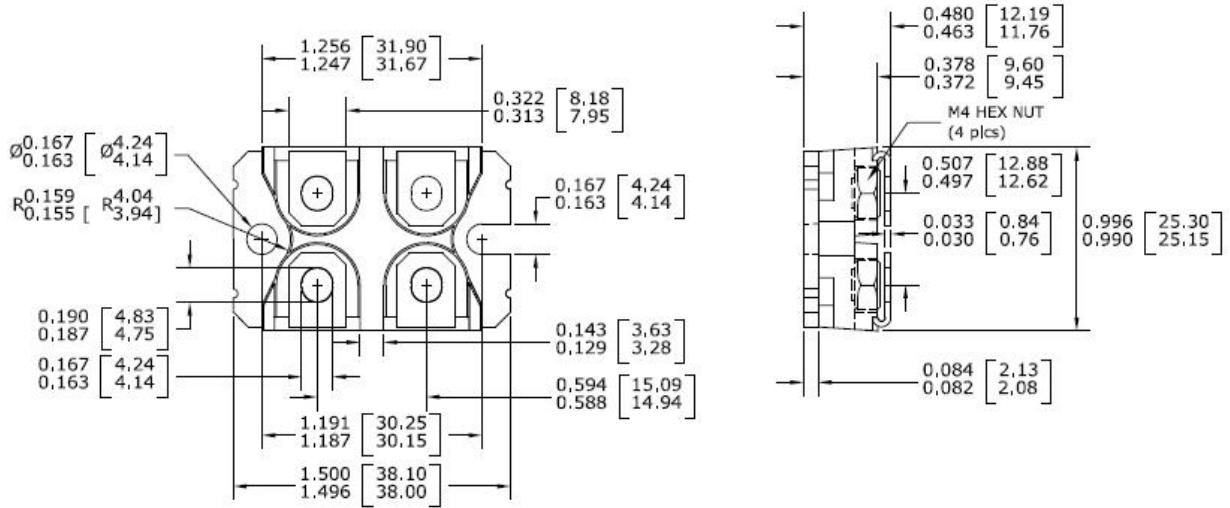
Thermal Resistance (per SCR)

| Parameter | Symbol | Max. Value | Units |
|--|------------|------------|---------------------------|
| Characteristics | | | |
| Thermal resistance, junction to case | R_{thJC} | 0.78 | $^\circ\text{C}/\text{W}$ |
| Isolation voltage, RMS (measured between terminals and mounting base, 50-60 Hz, for 1-2 seconds) | V_{iso} | 3000 | V |

Electrical Characteristics (per SCR), at $T_j = 25^\circ\text{C}$, unless otherwise specified

| Parameter | Symbol | Test Conditions | Value | | | Unit |
|--|--------------|---|-------|------|------|------------------|
| | | | Min. | Typ. | Max. | |
| Average on-state current | $I_{T(AV)}$ | $T_C = 85^\circ\text{C}$ 180° conduction half sine wave | - | - | 35 | A |
| Maximum on-state current, continuous RMS, AC switch | $I_{T(RMS)}$ | | - | - | 55 | |
| Maximum required DC gate current to trigger | I_{GT} | Anode Supply= 6V, $R_L = 33\Omega$ | - | 62 | 90 | mA |
| Maximum required DC gate voltage to trigger | V_{GT} | | - | 0.78 | 1.0 | V |
| Maximum DC gate voltage not to trigger | V_{GD} | $V_{DRM} = \text{rated value}$ | - | 0.25 | - | |
| Maximum DG gate current not to trigger | I_{GD} | | - | - | 6.0 | |
| Maximum holding current | I_H | $T_J = 25^\circ\text{C}$, anode supply 6 V, resistive load | - | 73.5 | 110 | mA |
| Maximum latching current | I_L | | - | 200 | 300 | |
| Maximum rate of rise of off-state voltage | dV/dt | $T_J = T_{Jmax}$ linear to 80% V_{DRM} | - | - | 1000 | V/ μs |
| Maximum peak on-state voltage | V_{TM} | 110 A | - | 1.55 | 1.8 | V |
| Maximum peak negative voltage | V_{RGM} | $I_{RG} = 100\text{mA}$ | - | - | 2 | |
| Threshold voltage, low level value $T_J = 125^\circ\text{C}$ | V_{TTO1} | $T_J = 125^\circ\text{C}$ | - | - | 1.02 | V |
| Threshold voltage, high level value $T_J = 125^\circ\text{C}$ | V_{TTO2} | | - | - | 1.23 | |
| Maximum peak gate power | P_{GM} | | - | 10 | - | W |
| Maximum average gate power | $P_{G(ave)}$ | | - | 2.5 | - | |
| On-state slope resistance, low level value $T_J = 125^\circ\text{C}$ | R_{t1} | $T_J = 125^\circ\text{C}$ | - | - | 9.74 | m |
| On-state slope resistance, high level value $T_J = 125^\circ\text{C}$ | R_{t2} | | - | - | 7.50 | |

Package Outline Drawing



CAUTION: These devices are ESD sensitive. Use proper handling procedure.

Disclaimer

These specifications may not be considered as a guarantee of components characteristics. Components have to be tested depending on intended application as adjustments may be necessary. The use of **iQXPRZ Power Inc.** components in life support appliances and systems are subject to written approval of **iQXPRZ Power Inc.**